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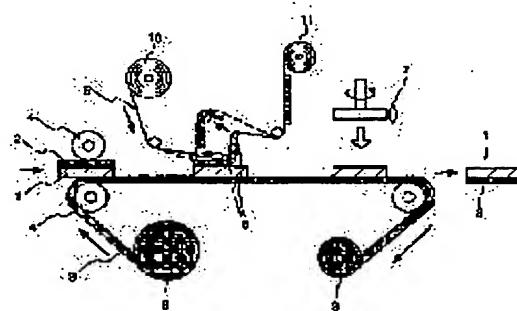
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(54) MANUFACTURE OF SEMICONDUCTOR DEVICE AND TAPE ADHERING AND PEELING APPARATUS

(57)Abstract:

PURPOSE: To eliminate a crack of a wafer due to vibration and impact during conveying of the wafer, removal from a wafer cassette, etc., by grinding a rear surface of the wafer, then adhering a reinforcing tape to the rear surface of the wafer, and peeling a protective tape adhered to an element forming surface.

CONSTITUTION: A wafer 1 adhered with a protective tape 2 is inserted into an adhering roller 4, a reinforcing tape 3 fed from a reinforcing tape roll 8 is adhered to a rear surface of the wafer 1 by the roller 4. Then, a peeling tape 5 fed from a peeling tape roll 10 is adhered to the tape 2 by a peeling roller 6, the tape 5 is peeled from the wafer 1, and the tape 5 is wound by a peeling tape winding roll 11. Thereafter, the tape 3 is cut by a cutter 7 to match a shape of the wafer 1. Then, a residue of the tape 3 cut by the cutter 7 is wound by a reinforcing tape winding roll 9. Thus, the tape 3 is adhered to hold a strength of the wafer 1.



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